



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10A226MR8NQDC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 22 µF, 4V, ±20%, X5R, 0603

## A. Samsung Part Number

<u>CL</u> <u>10</u> <u>A</u> <u>226</u> <u>M</u> <u>R</u> <u>8</u> <u>N</u> <u>Q</u> <u>D</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ 8 ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Ceramic Capacitor		
② Size	0603 (inch code)	L: 1.6 ± 0.15 mm	W: 0.8 ± 0.15 mm
③ Dielectric	X5R	Inner electrode	Ni
Capacitance	<b>22</b> μF	Termination	Cu
⑤ Capacitance	±20 %	Plating	Sn 100% (Pb Free)
tolerance		Product	0603 Size dimension spec
6 Rated Voltage	4 V	Special	Dc-bias aging
7 Thickness	0.8 ± 0.15 mm	① Packaging	Cardboard Type,7"reel(4,000ea)

## **B. Samsung Reliability Test and Judgement condition**

	Performance	Test condition	
Capacitance	Within specified tolerance	120Hz ±20% 0.5±0.1Vrms	
Tan δ (DF)	0.1 max.		
Insulation	More than 50Mohm⋅μF	Rated Voltage 60~120 sec.	
Resistance			
Appearance	No abnormal exterior appearance	Visual inspection	
Withstanding	No dielectric breakdown or	250% of the rated voltage	
Voltage	mechanical breakdown		
Temperature	X5R		
Characteristics	(From -55℃ to 85℃, Capacitance change should be within ±15%)		
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.	
of Termination	terminal electrode		
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)	
		with 1.0mm/sec.	
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder	
	is to be soldered newly	245±5°C, 3±0.3sec.	
		(preheating : 80~120 ℃ for 10~30sec.)	
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5 ℃, 10±1sec.	
Soldering heat	Tan δ, IR : initial spec.		

	Performance	Test condition
Vibration Test	Capacitance change: within ±5%	Amplitude : 1.5mm
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)
		2hours × 3 direction (x, y, z)
Moisture	Capacitance change: within ±12.5%	With rated voltage
Resistance	Tan δ : 0.25 max	40±2℃, 90~95%RH, 500 +12/-0 hours
	IR : More than 8.8MΩ·μF	
High Temperature	Capacitance change: within ±12.5%	With 100% of the rated voltage
Resistance	Tan δ : 0.25 max	Max. operating temperature
	IR : More than 17.7MΩ·μF	
		1000+48/-0 hours
Temperature	Capacitance change : within ±10%	1 cycle condition
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25 °C
		$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}{ m C}$
		5 cycles test

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C, 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.